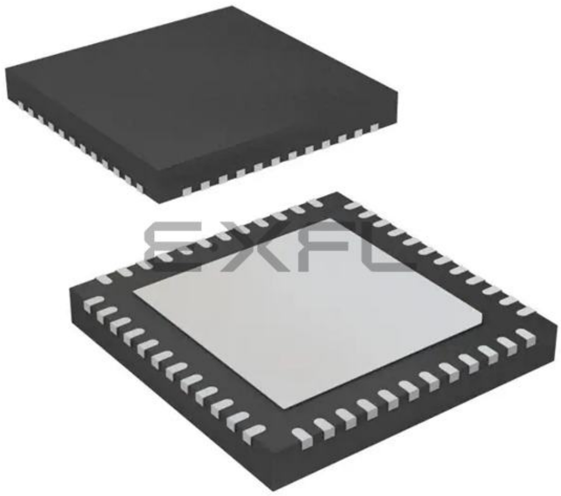


What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	35
Program Memory Size	128KB (43K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 9x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-UFQFN Exposed Pad
Supplier Device Package	48-UQFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep128mc204-i-mv

2.5 ICSP Pins

The PGECx and PGEDx pins are used for ICSP and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes, and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin Voltage Input High (V_{IH}) and Voltage Input Low (V_{IL}) requirements.

Ensure that the “Communication Channel Select” (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® PICkit™ 3, MPLAB ICD 3, or MPLAB REAL ICE™.

For more information on MPLAB ICD 2, ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site.

- *“Using MPLAB® ICD 3”* (poster) DS51765
- *“MPLAB® ICD 3 Design Advisory”* DS51764
- *“MPLAB® REAL ICE™ In-Circuit Emulator User’s Guide”* DS51616
- *“Using MPLAB® REAL ICE™ In-Circuit Emulator”* (poster) DS51749

2.6 External Oscillator Pins

Many DSCs have options for at least two oscillators: a high-frequency Primary Oscillator and a low-frequency Secondary Oscillator. For details, see **Section 9.0 “Oscillator Configuration”** for details.

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is shown in Figure 2-3.

FIGURE 2-3: SUGGESTED PLACEMENT OF THE OSCILLATOR CIRCUIT

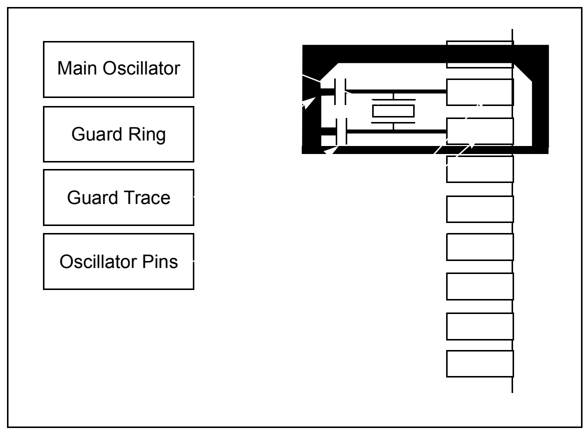


TABLE 4-52: PORTG REGISTER MAP FOR PIC24EPXXXGP/MC206 AND dsPIC33EPXXXGP/MC206/506 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISG	0E60	—	—	—	—	—	—	TRISG9	TRISG8	TRISG7	TRISG6	—	—	—	—	—	—	03C0
PORTG	0E62	—	—	—	—	—	—	RG9	RG8	RG7	RG6	—	—	—	—	—	—	xxxx
LATG	0E64	—	—	—	—	—	—	LATG9	LATG8	LATG7	LATG6	—	—	—	—	—	—	xxxx
ODCG	0E66	—	—	—	—	—	—	ODCG9	ODCG8	ODCG7	ODCG6	—	—	—	—	—	—	0000
CNENG	0E68	—	—	—	—	—	—	CNIEG9	CNIEG8	CNIEG7	CNIEG6	—	—	—	—	—	—	0000
CNPUG	0E6A	—	—	—	—	—	—	CNPUG9	CNPUG8	CNPUG7	CNPUG6	—	—	—	—	—	—	0000
CNPDG	0E6C	—	—	—	—	—	—	CNPDG9	CNPDG8	CNPDG7	CNPDG6	—	—	—	—	—	—	0000

Legend: x = unknown value on Reset, — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

TABLE 9-1: CONFIGURATION BIT VALUES FOR CLOCK SELECTION

Oscillator Mode	Oscillator Source	POSCMD<1:0>	FNOSC<2:0>	See Notes
Fast RC Oscillator with Divide-by-N (FRCDIVN)	Internal	xx	111	**1, 2**
Fast RC Oscillator with Divide-by-16 (FRCDIV16)	Internal	xx	110	**1**
Low-Power RC Oscillator (LPRC)	Internal	xx	101	**1**
Primary Oscillator (HS) with PLL (HSPLL)	Primary	10	011	
Primary Oscillator (XT) with PLL (XTPLL)	Primary	01	011	
Primary Oscillator (EC) with PLL (ECPLL)	Primary	00	011	**1**
Primary Oscillator (HS)	Primary	10	010	
Primary Oscillator (XT)	Primary	01	010	
Primary Oscillator (EC)	Primary	00	010	**1**
Fast RC Oscillator (FRC) with Divide-by-N and PLL (FRCPLL)	Internal	xx	001	**1**
Fast RC Oscillator (FRC)	Internal	xx	000	**1**

Note 1: OSC2 pin function is determined by the OSCIOFNC Configuration bit.
2: This is the default oscillator mode for an unprogrammed (erased) device.

9.2 Oscillator Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

9.2.1 KEY RESOURCES

- **"Oscillator"** (DS70580) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

9.3 Oscillator Control Registers

REGISTER 9-1: OSCCON: OSCILLATOR CONTROL REGISTER(1)

U-0	R-0	R-0	R-0	U-0	R/W-y	R/W-y	R/W-y
—	COSC2	COSC1	COSC0	—	NOSC2(2)	NOSC1(2)	NOSC0(2)
bit 15							bit 8

R/W-0	R/W-0	R-0	U-0	R/W-0	U-0	U-0	R/W-0
CLKLOCK	IOLOCK	LOCK	—	CF(3)	—	—	OSWEN
bit 7							bit 0

Legend:	y = Value set from Configuration bits on POR		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14-12 **COSC<2:0>:** Current Oscillator Selection bits (read-only)
111 = Fast RC Oscillator (FRC) with Divide-by-n
110 = Fast RC Oscillator (FRC) with Divide-by-16
101 = Low-Power RC Oscillator (LPRC)
100 = Reserved
011 = Primary Oscillator (XT, HS, EC) with PLL
010 = Primary Oscillator (XT, HS, EC)
001 = Fast RC Oscillator (FRC) with Divide-by-N and PLL (FRCPLL)
000 = Fast RC Oscillator (FRC)

bit 11 **Unimplemented:** Read as ‘0’

bit 10-8 **NOSC<2:0>:** New Oscillator Selection bits(2)
111 = Fast RC Oscillator (FRC) with Divide-by-n
110 = Fast RC Oscillator (FRC) with Divide-by-16
101 = Low-Power RC Oscillator (LPRC)
100 = Reserved
011 = Primary Oscillator (XT, HS, EC) with PLL
010 = Primary Oscillator (XT, HS, EC)
001 = Fast RC Oscillator (FRC) with Divide-by-N and PLL (FRCPLL)
000 = Fast RC Oscillator (FRC)

bit 7 **CLKLOCK:** Clock Lock Enable bit
1 = If (FCKSM0 = 1), then clock and PLL configurations are locked; if (FCKSM0 = 0), then clock and PLL configurations may be modified
0 = Clock and PLL selections are not locked, configurations may be modified

bit 6 **IOLOCK:** I/O Lock Enable bit
1 = I/O lock is active
0 = I/O lock is not active

bit 5 **LOCK:** PLL Lock Status bit (read-only)
1 = Indicates that PLL is in lock or PLL start-up timer is satisfied
0 = Indicates that PLL is out of lock, start-up timer is in progress or PLL is disabled

Note 1: Writes to this register require an unlock sequence. Refer to **“Oscillator”** (DS70580) in the *“dsPIC33/PIC24 Family Reference Manual”* (available from the Microchip web site) for details.

2: Direct clock switches between any primary oscillator mode with PLL and FRCPLL mode are not permitted. This applies to clock switches in either direction. In these instances, the application must switch to FRC mode as a transitional clock source between the two PLL modes.

3: This bit should only be cleared in software. Setting the bit in software (= 1) will have the same effect as an actual oscillator failure and trigger an oscillator failure trap.

12.0 TIMER1

> **Note 1:** This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Timers"** (DS70362) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).
>
> **2:** Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Timer1 module is a 16-bit timer that can operate as a free-running interval timer/counter.

The Timer1 module has the following unique features over other timers:

- Can be operated in Asynchronous Counter mode from an external clock source
- The external clock input (T1CK) can optionally be synchronized to the internal device clock and the clock synchronization is performed after the prescaler

A block diagram of Timer1 is shown in Figure 12-1.

The Timer1 module can operate in one of the following modes:

- Timer mode
- Gated Timer mode
- Synchronous Counter mode
- Asynchronous Counter mode

In Timer and Gated Timer modes, the input clock is derived from the internal instruction cycle clock (FCY). In Synchronous and Asynchronous Counter modes, the input clock is derived from the external clock input at the T1CK pin.

The Timer modes are determined by the following bits:

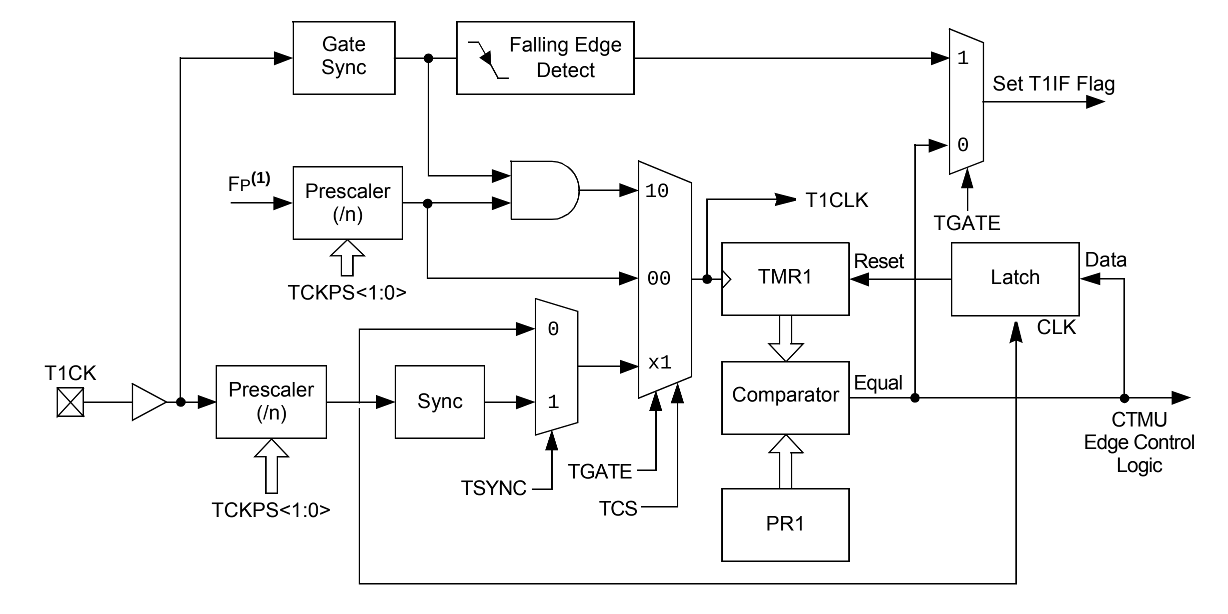
- Timer Clock Source Control bit (TCS): T1CON<1>
- Timer Synchronization Control bit (TSYNC): T1CON<2>
- Timer Gate Control bit (TGATE): T1CON<6>

Timer control bit setting for different operating modes are given in the Table 12-1.

TABLE 12-1: TIMER MODE SETTINGS

Mode	TCS	TGATE	TSYNC
Timer	0	0	x
Gated Timer	0	1	x
Synchronous Counter	1	x	1
Asynchronous Counter	1	x	0

FIGURE 12-1: 16-BIT TIMER1 MODULE BLOCK DIAGRAM



Note 1: FP is the peripheral clock.

REGISTER 14-2: ICxCON2: INPUT CAPTURE x CONTROL REGISTER 2 (CONTINUED)

bit 4-0 **SYNCSEL<4:0>:** Input Source Select for Synchronization and Trigger Operation bits[4]

`11111` = No Sync or Trigger source for ICx
`11110` = Reserved
`11101` = Reserved
`11100` = CTMU module synchronizes or triggers ICx
`11011` = ADC1 module synchronizes or triggers ICx[5]
`11010` = CMP3 module synchronizes or triggers ICx[5]
`11001` = CMP2 module synchronizes or triggers ICx[5]
`11000` = CMP1 module synchronizes or triggers ICx[5]
`10111` = Reserved
`10110` = Reserved
`10101` = Reserved
`10100` = Reserved
`10011` = IC4 module synchronizes or triggers ICx
`10010` = IC3 module synchronizes or triggers ICx
`10001` = IC2 module synchronizes or triggers ICx
`10000` = IC1 module synchronizes or triggers ICx
`01111` = Timer5 synchronizes or triggers ICx
`01110` = Timer4 synchronizes or triggers ICx
`01101` = Timer3 synchronizes or triggers ICx **(default)**
`01100` = Timer2 synchronizes or triggers ICx
`01011` = Timer1 synchronizes or triggers ICx
`01010` = PTGOx module synchronizes or triggers ICx[6]
`01001` = Reserved
`01000` = Reserved
`00111` = Reserved
`00110` = Reserved
`00101` = Reserved
`00100` = OC4 module synchronizes or triggers ICx
`00011` = OC3 module synchronizes or triggers ICx
`00010` = OC2 module synchronizes or triggers ICx
`00001` = OC1 module synchronizes or triggers ICx
`00000` = No Sync or Trigger source for ICx

Note 1: The IC32 bit in both the Odd and Even IC must be set to enable Cascade mode.

2: The input source is selected by the SYNCSEL<4:0> bits of the ICxCON2 register.

3: This bit is set by the selected input source (selected by SYNCSEL<4:0> bits). It can be read, set and cleared in software.

4: Do not use the ICx module as its own Sync or Trigger source.

5: This option should only be selected as a trigger source and not as a synchronization source.

6: Each Input Capture x (ICx) module has one PTG input source. See **Section 24.0 "Peripheral Trigger Generator (PTG) Module"** for more information.
PTGO8 = IC1
PTGO9 = IC2
PTGO10 = IC3
PTGO11 = IC4

16.0 HIGH-SPEED PWM MODULE (dsPIC33EPXXXMC20X/50X AND PIC24EPXXXMC20X DEVICES ONLY)

Note 1:	This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"High-Speed PWM"** (DS70645) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).
2:	Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices support a dedicated Pulse-Width Modulation (PWM) module with up to 6 outputs.

The high-speed PWMx module consists of the following major features:

- Three PWM generators
- Two PWM outputs per PWM generator
- Individual period and duty cycle for each PWM pair
- Duty cycle, dead time, phase shift and frequency resolution of $T_{CY}/2$ (7.14 ns at F_{CY} = 70MHz)
- Independent Fault and current-limit inputs for six PWM outputs
- Redundant output
- Center-Aligned PWM mode
- Output override control
- Chop mode (also known as Gated mode)
- Special Event Trigger
- Prescaler for input clock
- PWMxL and PWMxH output pin swapping
- Independent PWM frequency, duty cycle and phase-shift changes for each PWM generator
- Dead-time compensation
- Enhanced Leading-Edge Blanking (LEB) functionality
- Frequency resolution enhancement
- PWM capture functionality

Note:	In Edge-Aligned PWM mode, the duty cycle, dead time, phase shift and frequency resolution are 8.32 ns.

The high-speed PWMx module contains up to three PWM generators. Each PWM generator provides two PWM outputs: PWMxH and PWMxL. The master time base generator provides a synchronous signal as a common time base to synchronize the various PWM outputs. The individual PWM outputs are available on the output pins of the device. The input Fault signals and current-limit signals, when enabled, can monitor and protect the system by placing the PWM outputs into a known "safe" state.

Each PWMx can generate a trigger to the ADC module to sample the analog signal at a specific instance during the PWM period. In addition, the high-speed PWMx module also generates a Special Event Trigger to the ADC module based on either of the two master time bases.

The high-speed PWMx module can synchronize itself with an external signal or can act as a synchronizing source to any external device. The SYNCI1 input pin that utilizes PPS, can synchronize the high-speed PWMx module with an external signal. The SYNCO1 pin is an output pin that provides a synchronous signal to an external device.

Figure 16-1 illustrates an architectural overview of the high-speed PWMx module and its interconnection with the CPU and other peripherals.

16.1 PWM Faults

The PWMx module incorporates multiple external Fault inputs to include FLT1 and FLT2 which are remappable using the PPS feature, FLT3 and FLT4 which are available only on the larger 44-pin and 64-pin packages, and FLT32 which has been implemented with Class B safety features, and is available on a fixed pin on all dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices.

These Faults provide a safe and reliable way to safely shut down the PWM outputs when the Fault input is asserted.

16.1.1 PWM FAULTS AT RESET

During any Reset event, the PWMx module maintains ownership of the Class B Fault, FLT32. At Reset, this Fault is enabled in Latched mode to ensure the fail-safe power-up of the application. The application software must clear the PWM Fault before enabling the high-speed motor control PWMx module. To clear the Fault condition, the FLT32 pin must first be pulled low externally or the internal pull-down resistor in the CNPDx register can be enabled.

Note:	The Fault mode may be changed using the FLTMOD<1:0> bits (FCLCON<1:0>), regardless of the state of FLT32.

16.1.2 WRITE-PROTECTED REGISTERS

On dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices, write protection is implemented for the IOCONx and FCLCONx registers. The write protection feature prevents any inadvertent writes to these registers. This protection feature can be controlled by the PWMLOCK Configuration bit (FOSCSEL<6>). The default state of the write protection feature is enabled (PWMLOCK = 1). The write protection feature can be disabled by configuring, PWMLOCK = 0.

To gain write access to these locked registers, the user application must write two consecutive values of (0xABCD and 0x4321) to the PWMKEY register to perform the unlock operation. The write access to the IOCONx or FCLCONx registers must be the next SFR access following the unlock process. There can be no other SFR accesses during the unlock process and subsequent write access. To write to both the IOCONx and FCLCONx registers requires two unlock operations.

The correct unlocking sequence is described in Example 16-1.

EXAMPLE 16-1: PWMx WRITE-PROTECTED REGISTER UNLOCK SEQUENCE

```
; FLT32 pin must be pulled low externally in order to clear and disable the fault
; Writing to FCLCON1 register requires unlock sequence

mov #0xabcd,w10       ; Load first unlock key to w10 register
mov #0x4321,w11       ; Load second unlock key to w11 register
mov #0x0000,w0        ; Load desired value of FCLCON1 register in w0
mov w10, PWMKEY       ; Write first unlock key to PWMKEY register
mov w11, PWMKEY       ; Write second unlock key to PWMKEY register
mov w0,FCLCON1        ; Write desired value to FCLCON1 register

; Set PWM ownership and polarity using the IOCON1 register
; Writing to IOCON1 register requires unlock sequence

mov #0xabcd,w10       ; Load first unlock key to w10 register
mov #0x4321,w11       ; Load second unlock key to w11 register
mov #0xF000,w0        ; Load desired value of IOCON1 register in w0
mov w10, PWMKEY       ; Write first unlock key to PWMKEY register
mov w11, PWMKEY       ; Write second unlock key to PWMKEY register
mov w0,IOCON1         ; Write desired value to IOCON1 register
```

REGISTER 16-10: DTRx: PWMx DEAD-TIME REGISTER

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	DTRx<13:8>					
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
DTRx<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13-0 **DTRx<13:0>:** Unsigned 14-Bit Dead-Time Value for PWMx Dead-Time Unit bits

REGISTER 16-11: ALTDTRx: PWMx ALTERNATE DEAD-TIME REGISTER

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	ALTDTRx<13:8>					
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ALTDTRx<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13-0 **ALTDTRx<13:0>:** Unsigned 14-Bit Dead-Time Value for PWMx Dead-Time Unit bits

20.1 UART Helpful Tips

1. In multi-node, direct-connect UART networks, UART receive inputs react to the complementary logic level defined by the URXINV bit (UxMODE<4>), which defines the Idle state, the default of which is logic high (i.e., URXINV = 0). Because remote devices do not initialize at the same time, it is likely that one of the devices, because the RX line is floating, will trigger a Start bit detection and will cause the first byte received, after the device has been initialized, to be invalid. To avoid this situation, the user should use a pull-up or pull-down resistor on the RX pin depending on the value of the URXINV bit.
   a) If URXINV = 0, use a pull-up resistor on the RX pin.
   b) If URXINV = 1, use a pull-down resistor on the RX pin.
2. The first character received on a wake-up from Sleep mode caused by activity on the UxRX pin of the UARTx module will be invalid. In Sleep mode, peripheral clocks are disabled. By the time the oscillator system has restarted and stabilized from Sleep mode, the baud rate bit sampling clock, relative to the incoming UxRX bit timing, is no longer synchronized, resulting in the first character being invalid; this is to be expected.

20.2 UART Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

20.2.1 KEY RESOURCES

- **"UART"** (DS70582) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

REGISTER 21-15: CxBUFPNT4: ECANx FILTER 12-15 BUFFER POINTER REGISTER 4

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F15BP<3:0>				F14BP<3:0>			
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F13BP<3:0>				F12BP<3:0>			
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-12 **F15BP<3:0>:** RX Buffer Mask for Filter 15 bits
`1111` = Filter hits received in RX FIFO buffer
`1110` = Filter hits received in RX Buffer 14
•
•
•
`0001` = Filter hits received in RX Buffer 1
`0000` = Filter hits received in RX Buffer 0

bit 11-8 **F14BP<3:0>:** RX Buffer Mask for Filter 14 bits (same values as bits<15:12>)

bit 7-4 **F13BP<3:0>:** RX Buffer Mask for Filter 13 bits (same values as bits<15:12>)

bit 3-0 **F12BP<3:0>:** RX Buffer Mask for Filter 12 bits (same values as bits<15:12>)

REGISTER 21-19: CxFMSKSEL2: ECANx FILTER 15-8 MASK SELECTION REGISTER 2

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F15MSK<1:0>		F14MSK<1:0>		F13MSK<1:0>		F12MSK<1:0>	
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F11MSK<1:0>		F10MSK<1:0>		F9MSK<1:0>		F8MSK<1:0>	
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **F15MSK<1:0>:** Mask Source for Filter 15 bits
`11` = Reserved
`10` = Acceptance Mask 2 registers contain mask
`01` = Acceptance Mask 1 registers contain mask
`00` = Acceptance Mask 0 registers contain mask

bit 13-12 **F14MSK<1:0>:** Mask Source for Filter 14 bits (same values as bits<15:14>)

bit 11-10 **F13MSK<1:0>:** Mask Source for Filter 13 bits (same values as bits<15:14>)

bit 9-8 **F12MSK<1:0>:** Mask Source for Filter 12 bits (same values as bits<15:14>)

bit 7-6 **F11MSK<1:0>:** Mask Source for Filter 11 bits (same values as bits<15:14>)

bit 5-4 **F10MSK<1:0>:** Mask Source for Filter 10 bits (same values as bits<15:14>)

bit 3-2 **F9MSK<1:0>:** Mask Source for Filter 9 bits (same values as bits<15:14>)

bit 1-0 **F8MSK<1:0>:** Mask Source for Filter 8 bits (same values as bits<15:14>)

BUFFER 21-3: ECAN™ MESSAGE BUFFER WORD 2

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
EID5	EID4	EID3	EID2	EID1	EID0	RTR	RB1
bit 15							bit 8

U-x	U-x	U-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	RB0	DLC3	DLC2	DLC1	DLC0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-10 **EID<5:0>:** Extended Identifier bits

bit 9 **RTR:** Remote Transmission Request bit
When IDE = `1`:
`1` = Message will request remote transmission
`0` = Normal message
When IDE = `0`:
The RTR bit is ignored.

bit 8 **RB1:** Reserved Bit 1
User must set this bit to ‘`0`’ per CAN protocol.

bit 7-5 **Unimplemented:** Read as ‘`0`’

bit 4 **RB0:** Reserved Bit 0
User must set this bit to ‘`0`’ per CAN protocol.

bit 3-0 **DLC<3:0>:** Data Length Code bits

BUFFER 21-4: ECAN™ MESSAGE BUFFER WORD 3

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 1							
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 0							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **Byte 1<15:8>:** ECAN Message Byte 1 bits

bit 7-0 **Byte 0<7:0>:** ECAN Message Byte 0 bits

27.0 SPECIAL FEATURES

> **Note:** This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the related section of the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices include several features intended to maximize application flexibility and reliability, and minimize cost through elimination of external components. These are:

- Flexible Configuration
- Watchdog Timer (WDT)
- Code Protection and CodeGuard™ Security
- JTAG Boundary Scan Interface
- In-Circuit Serial Programming™ (ICSP™)
- In-Circuit Emulation

27.1 Configuration Bits

In dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices, the Configuration bytes are implemented as volatile memory. This means that configuration data must be programmed each time the device is powered up. Configuration data is stored in at the top of the on-chip program memory space, known as the Flash Configuration bytes. Their specific locations are shown in Table 27-1. The configuration data is automatically loaded from the Flash Configuration bytes to the proper Configuration Shadow registers during device Resets.

> **Note:** Configuration data is reloaded on all types of device Resets.

When creating applications for these devices, users should always specifically allocate the location of the Flash Configuration bytes for configuration data in their code for the compiler. This is to make certain that program code is not stored in this address when the code is compiled.

The upper 2 bytes of all Flash Configuration Words in program memory should always be '`1111 1111 1111 1111`'. This makes them appear to be `NOP` instructions in the remote event that their locations are ever executed by accident. Since Configuration bits are not implemented in the corresponding locations, writing '`1`'s to these locations has no effect on device operation.

> **Note:** Performing a page erase operation on the last page of program memory clears the Flash Configuration bytes, enabling code protection as a result. Therefore, users should avoid performing page erase operations on the last page of program memory.

The Configuration Flash bytes map is shown in Table 27-1.

TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax	Description	# of Words	# of Cycles(2)	Status Flags Affected
52	MUL	MUL.SS Wb,Ws,Wnd	{Wnd + 1, Wnd} = signed(Wb) * signed(Ws)	1	1	None
		MUL.SS Wb,Ws,Acc(1)	Accumulator = signed(Wb) * signed(Ws)	1	1	None
		MUL.SU Wb,Ws,Wnd	{Wnd + 1, Wnd} = signed(Wb) * unsigned(Ws)	1	1	None
		MUL.SU Wb,Ws,Acc(1)	Accumulator = signed(Wb) * unsigned(Ws)	1	1	None
		MUL.SU Wb,#lit5,Acc(1)	Accumulator = signed(Wb) * unsigned(lit5)	1	1	None
		MUL.US Wb,Ws,Wnd	{Wnd + 1, Wnd} = unsigned(Wb) * signed(Ws)	1	1	None
		MUL.US Wb,Ws,Acc(1)	Accumulator = unsigned(Wb) * signed(Ws)	1	1	None
		MUL.UU Wb,Ws,Wnd	{Wnd + 1, Wnd} = unsigned(Wb) * unsigned(Ws)	1	1	None
		MUL.UU Wb,#lit5,Acc(1)	Accumulator = unsigned(Wb) * unsigned(lit5)	1	1	None
		MUL.UU Wb,Ws,Acc(1)	Accumulator = unsigned(Wb) * unsigned(Ws)	1	1	None
		MULW.SS Wb,Ws,Wnd	Wnd = signed(Wb) * signed(Ws)	1	1	None
		MULW.SU Wb,Ws,Wnd	Wnd = signed(Wb) * unsigned(Ws)	1	1	None
		MULW.US Wb,Ws,Wnd	Wnd = unsigned(Wb) * signed(Ws)	1	1	None
		MULW.UU Wb,Ws,Wnd	Wnd = unsigned(Wb) * unsigned(Ws)	1	1	None
		MUL.SU Wb,#lit5,Wnd	{Wnd + 1, Wnd} = signed(Wb) * unsigned(lit5)	1	1	None
		MUL.SU Wb,#lit5,Wnd	Wnd = signed(Wb) * unsigned(lit5)	1	1	None
		MUL.UU Wb,#lit5,Wnd	{Wnd + 1, Wnd} = unsigned(Wb) * unsigned(lit5)	1	1	None
		MUL.UU Wb,#lit5,Wnd	Wnd = unsigned(Wb) * unsigned(lit5)	1	1	None
		MUL f	W3:W2 = f * WREG	1	1	None

Note 1: These instructions are available in dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.
2: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

TABLE 30-9: DC CHARACTERISTICS: WATCHDOG TIMER DELTA CURRENT (ΔIWDT)(1)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended		
Parameter No.	**Typ.**	**Max.**	**Units**	**Conditions**	
DC61d	8	—	μA	-40°C	3.3V
DC61a	10	—	μA	+25°C	
DC61b	12	—	μA	+85°C	
DC61c	13	—	μA	+125°C	

Note 1: The ΔIWDT current is the additional current consumed when the module is enabled. This current should be added to the base IPD current. All parameters are characterized but not tested during manufacturing.

TABLE 30-10: DC CHARACTERISTICS: DOZE CURRENT (IDOZE)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Parameter No.	**Typ.**	**Max.**	**Doze Ratio**	**Units**	**Conditions**		
Doze Current (IDOZE)(1)							
DC73a(2)	35	—	1:2	mA	-40°C	3.3V	FOSC = 140 MHz
DC73g	20	30	1:128	mA			
DC70a(2)	35	—	1:2	mA	+25°C	3.3V	FOSC = 140 MHz
DC70g	20	30	1:128	mA			
DC71a(2)	35	—	1:2	mA	+85°C	3.3V	FOSC = 140 MHz
DC71g	20	30	1:128	mA			
DC72a(2)	28	—	1:2	mA	+125°C	3.3V	FOSC = 120 MHz
DC72g	15	30	1:128	mA			

Note 1: IDOZE is primarily a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption. The test conditions for all IDOZE measurements are as follows:

- Oscillator is configured in EC mode and external clock is active, OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{\text{MCLR}}$ = VDD, WDT and FSCM are disabled
- CPU, SRAM, program memory and data memory are operational
- No peripheral modules are operating; however, every peripheral is being clocked (all PMDx bits are zeroed)
- CPU is executing `while(1)` statement
- JTAG is disabled

2: Parameter is characterized but not tested in manufacturing.

TABLE 30-38: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 1, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic[1]**	**Min.**	**Typ.[2]**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK2 Input Frequency	—	—	Lesser of FP or 11	MHz	**(Note 3)**
SP72	TscF	SCK2 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK2 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO2 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO2 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO2 Data Output Valid after SCK2 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO2 Data Output Setup to First SCK2 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{\text{SS2}}$ ↓ to SCK2 ↑ or SCK2 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{\text{SS2}}$ ↑ to SDO2 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH TscL2ssH	$\overline{\text{SS2}}$ ↑ after SCK2 Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**
SP60	TssL2doV	SDO2 Data Output Valid after $\overline{\text{SS2}}$ Edge	—	—	50	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK2 is 91 ns. Therefore, the SCK2 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI2 pins.

TABLE 30-46: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 1, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK1 Input Frequency	—	—	Lesser of FP or 11	MHz	**(Note 3)**
SP72	TscF	SCK1 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK1 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO1 Data Output Setup to First SCK1 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SS1}$ ↓ to SCK1 ↑ or SCK1 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SS1}$ ↑ to SDO1 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH, TscL2ssH	$\overline{SS1}$ ↑ after SCK1 Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**
SP60	TssL2doV	SDO1 Data Output Valid after $\overline{SS1}$ Edge	—	—	50	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK1 is 91 ns. Therefore, the SCK1 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI1 pins.

TABLE 30-58: ADC MODULE SPECIFICATIONS (12-BIT MODE)

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)(1) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
ADC Accuracy (12-Bit Mode)							
AD20a	Nr	Resolution	12 Data Bits			bits	
AD21a	INL	Integral Nonlinearity	-2.5	—	2.5	LSb	-40°C ≤ TA ≤ +85°C **(Note 2)**
			-5.5	—	5.5	LSb	+85°C < TA ≤ +125°C **(Note 2)**
AD22a	DNL	Differential Nonlinearity	-1	—	1	LSb	-40°C ≤ TA ≤ +85°C **(Note 2)**
			-1	—	1	LSb	+85°C < TA ≤ +125°C **(Note 2)**
AD23a	GERR	Gain Error(3)	-10	—	10	LSb	-40°C ≤ TA ≤ +85°C **(Note 2)**
			-10	—	10	LSb	+85°C < TA ≤ +125°C **(Note 2)**
AD24a	EOFF	Offset Error	-5	—	5	LSb	-40°C ≤ TA ≤ +85°C **(Note 2)**
			-5	—	5	LSb	+85°C < TA ≤ +125°C **(Note 2)**
AD25a	—	Monotonicity	—	—	—	—	Guaranteed
Dynamic Performance (12-Bit Mode)							
AD30a	THD	Total Harmonic Distortion(3)	—	75	—	dB	
AD31a	SINAD	Signal to Noise and Distortion(3)	—	68	—	dB	
AD32a	SFDR	Spurious Free Dynamic Range(3)	—	80	—	dB	
AD33a	FNYQ	Input Signal Bandwidth(3)	—	250	—	kHz	
AD34a	ENOB	Effective Number of Bits(3)	11.09	11.3	—	bits	

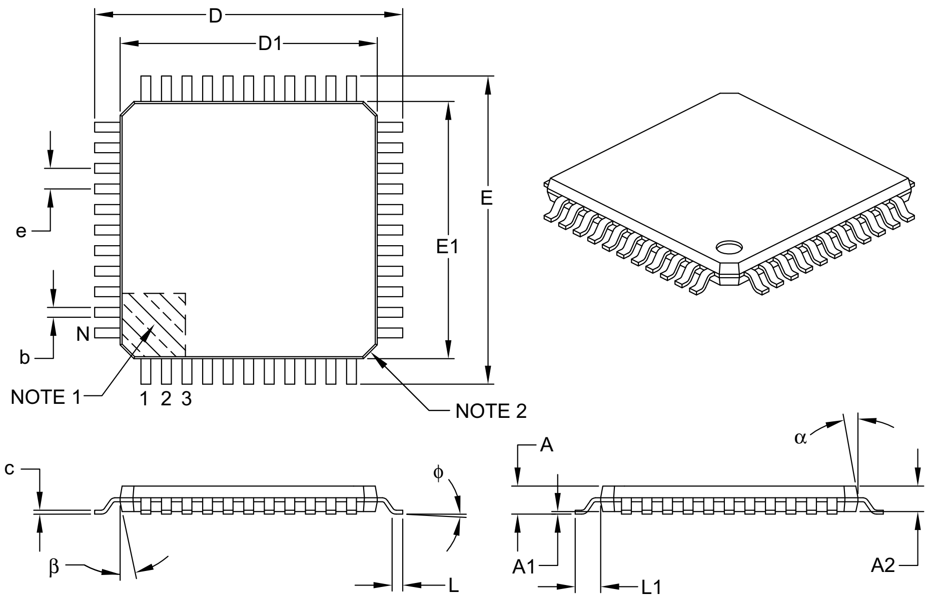
Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

2: For all accuracy specifications, VINL = AVSS = VREFL = 0V and AVDD = VREFH = 3.6V.

3: Parameters are characterized but not tested in manufacturing.

44-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N	44		
Lead Pitch	e	0.80 BSC		
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1	1.00 REF		
Foot Angle	φ	0°	3.5°	7°
Overall Width	E	12.00 BSC		
Overall Length	D	12.00 BSC		
Molded Package Width	E1	10.00 BSC		
Molded Package Length	D1	10.00 BSC		
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.30	0.37	0.45
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-076B